

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

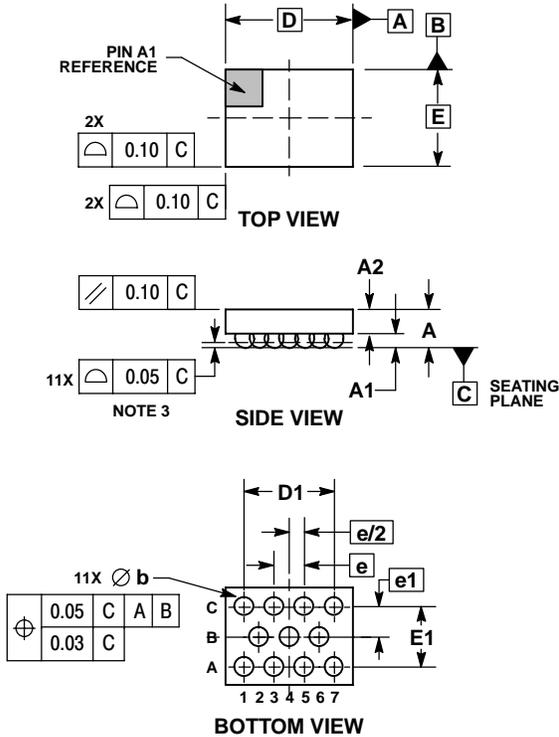


A1

SCALE 4:1

11 PIN FLIP-CHIP, 2.04x1.41, 0.5P
CASE 766AJ-01
ISSUE O

DATE 07 MAR 2007



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.66
A1	0.21	0.27
A2	0.33	0.39
b	0.29	0.34
D	2.04 BSC	
D1	1.50 BSC	
E	1.41 BSC	
E1	0.86 BSC	
e	0.50 BSC	
e1	0.43 BSC	

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	11 PIN FLIP-CHIP, 2.04 X 1.41, 0.5P	PAGE 1 OF 2

